imall

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40V MATCHED PAIR PNP SMALL SIGNAL TRANSISTOR IN SOT363

Features

- BV_{CEO} > -40V
- I_C = -200mA High Collector Current
- Pair of PNP Transistors That Are Intrinsically Matched (Note 1)
- 2% Matching on Current Gain (h_{FE})
- 2mV Matching on Base-Emitter Voltage (V_{BE})
- Fully Internally Isolated in a Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 2 & 3)
- Halogen and Antimony Free. "Green" Device (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 5)

Mechanical Data

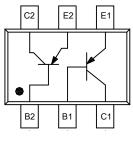
- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.006 grams (approximate)

Applications

- Current Mirrors
- Differential and Instrumentation Amplifiers
- Comparators



Top View



Device Schematic and Pin-Out Top View

Ordering Information (Note 4 & 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DMMT3906W-7-F	AEC-Q101	K4B	7	8	3,000
DMMT3906WQ-7-F	Automotive	K4B	7	8	3,000

Notes:

1. Intrinsically matched pair as this is built with adjacent die from the same wafer.

2. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

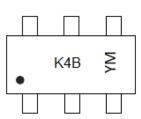
3. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

4. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

5. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.

6. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



K4B = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 2 = February)

Date Code Key

Year	2010	201	1	2012	20	013	2014		2015	2016		2017
Tear	2010	20		2012	20	/13	2014	4	.015	2010		2017
Code	Х	Y		Z		A	В		С	D		E
Month	Jan	Feb	Mar	Apr	Mav	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-40	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	lc	-200	mA

Thermal Characteristics – Total Device (@TA = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7) Total Device	PD	200	mW
Thermal Resistance, Junction to Ambient (Note 7)	$R_{ ext{ heta}JA}$	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

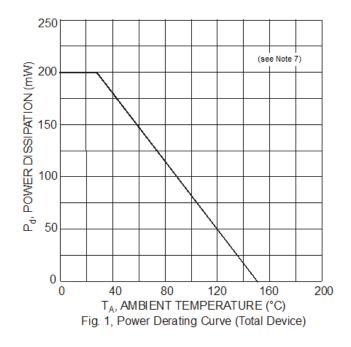
ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Note: 7. For a device mounted on minimum recommended pad layout with 1oz copper that is on a single-sided 1.6mm FR4 PCB; the device is measured under still air conditions whilst operating in a steady-state.

8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics – Total Device





Electrical Characteristics (@T_A = +25°C unless otherwise specified)

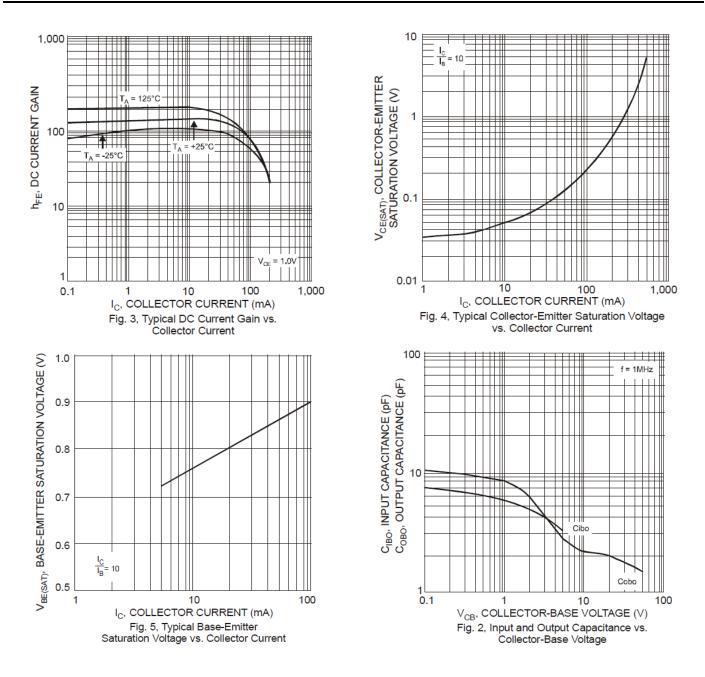
Characteristic	Symbol	Min	TYP	Мах	Unit	Test Condition
OFF CHARACTERISTICS	•			•		+
Collector-Base Breakdown Voltage	BV _{CBO}	-40	_	_	V	$I_{\rm C}$ = -100µA, $I_{\rm E}$ = 0
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	-40	—	_	V	I _C = -1.0mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	-5.0	_	_	V	$I_{\rm E} = -100 \mu A, I_{\rm C} = 0$
Collector Cutoff Current	I _{CEX}	_	_	-50	nA	V _{CE} = -30V, V _{EB(OFF)} = 3.0V
Base Cutoff Current	I _{BL}	_	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = 3.0V$
ON CHARACTERISTICS (Note 9)						•
DC Current Gain	h _{FE}	60 80 100 60 30	_	 300 		$\begin{split} I_C &= -100 \mu A, \ V_{CE} &= -1.0V \\ I_C &= -1.0mA, \ V_{CE} &= -1.0V \\ I_C &= -10mA, \ V_{CE} &= -1.0V \\ I_C &= -50mA, \ V_{CE} &= -1.0V \\ I_C &= -100mA, \ V_{CE} &= -1.0V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		_	-250 -400	mV	I_{C} = -10mA, I_{B} = -1.0mA I_{C} = -50mA, I_{B} = -5.0mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.65		-850 -950	mV	I _C = -10mA, I _B = -1.0mA I _C = -50mA, I _B = -5.0mA
MATCHING CHARACTERISTICS			•	1	•	
DC Current Gain Matching (Note 10)	h_{FE1} / h_{FE2}	_	1	2	%	$I_{\rm C}$ = -2mA, $V_{\rm CE}$ = -5V
Base-Emitter Voltage Matching (Note 11)	V _{BE1} - V _{BE2}	—	1	2	mV	I _C = -2mA, V _{CE} = -5V
Collector-Emitter Saturation Voltage (Note 10)	V _{CE(SAT)1} / V _{CE(SAT)2}	—	1	2	%	I _C = -10mA, I _B = -1.0mA
Base-Emitter Saturation Voltage (Note 10)	V _{BE(SAT)1} / V _{BE(SAT)2}	—	1	2	%	I _C = -10mA, I _B = -1.0mA
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C _{obo}	—	—	4.5	pF	V_{CB} = -5.0V, f = 1.0MHz, I _E = 0
Input Capacitance	Cibo	—	—	10.0	pF	V_{EB} = -0.5V, f = 1.0MHz, I _C = 0
Input Impedance	h _{ie}	2.0	—	12	kΩ	
Voltage Feedback Ratio	h _{re}	0.1	—	10	x 10 ⁻⁴	V _{CE} = 10V, I _C = 1.0mA,
Small Signal Current Gain	h _{fe}	100	—	400	—	f = 1.0kHz
Output Admittance	h _{oe}	3.0	—	60	μS	
Current Gain-Bandwidth Product	f _T	250	_	_	MHz	V _{CE} = -20V, I _C = -10mA, f = 100MHz
Noise Figure	NF	_	_	4.0	dB	V_{CE} = -5.0V, I _C = -100µA, R _S = 1.0kΩ, f = 1.0kHz
SWITCHING CHARACTERISTICS			-	-		
Delay Time	t _d	_	—	35	ns	V _{CC} = -3.0V, I _C = -10mA,
Rise Time	tr	_	—	35	ns	$V_{BE(off)} = 0.5V, I_{B1} = -1.0mA$
Storage Time	ts			225	ns	V _{CC} = -3.0V, I _C = -10mA,
Fall Time	t _f		_	75	ns	I _{B1} = I _{B2} = -1.0mA

Note:

9. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.
10. Is the ratio of one transistor compared to the other transistor.
11. V_{BE1} - V_{BE2} is the absolute difference of one transistor compared to the other transistor.



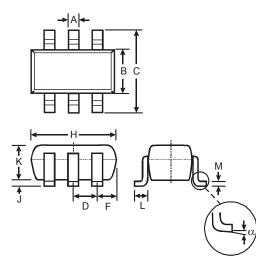
Typical Electrical Characteristics (@T_A = +25°C unless otherwise specified.)





Package Outline Dimensions

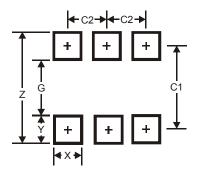
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT363						
Dim	Min	Max	Тур				
Α	0.10	0.30	0.25				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D		0.65 Ty	р				
F	0.40	0.45	0.425				
Н	1.80	2.20	2.15				
J	0	0.10	0.05				
κ	0.90	1.00	1.00				
L	0.25	0.40	0.30				
Μ	0.10	0.22	0.11				
α	0°	8°	-				
All	Dimen	isions i	n mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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